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Circuit boards and circuit board assemblies — Design and use

Part 8: 3D shape data for CAD component library

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National foreword

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CIRCUIT BOARDS AND CIRCUIT BOARD ASSEMBLIES – DESIGN AND USE –

Part 8: 3D shape data for CAD component library

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IEC 61188-8 has been prepared by IEC technical committee 91: Electronics assembly technology. It is a Technical Report.

The text of this Technical Report is based on the following documents:

Draft	Report on voting
91/1640/DTR	91/1682/RVDTR

Full information on the voting for its approval can be found in the report on voting indicated in the above table.

The language used for the development of this Technical Report is English.

This document was drafted in accordance with ISO/IEC Directives, Part 2, and developed in accordance with ISO/IEC Directives, Part 1 and ISO/IEC Directives, IEC Supplement, available at www.iec.ch/members_experts/refdocs. The main document types developed by IEC are described in greater detail at www.iec.ch/standardsdev/publications.

A list of all parts in the IEC 61188 series, published under the general title *Circuit boards and circuit board assemblies – Design and use*, can be found on the IEC website.

The committee has decided that the contents of this document will remain unchanged until the stability date indicated on the IEC website under "http://webstore.iec.ch" in the data related to the specific document. At this date, the document will be

- reconfirmed,
- withdrawn,
- replaced by a revised edition, or
- amended.

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CIRCUIT BOARDS AND CIRCUIT BOARD ASSEMBLIES – DESIGN AND USE –

Part 8: 3D shape data for CAD component library

1 Scope

This part of IEC 61188 describes the configuration of part shape data of semiconductor devices and electrical components registered in the CAD library.

This document mainly describes the configuration of 2D and 3D parts shape data.

2 Normative references

There are no normative references in this document.

3 Terms, definitions and abbreviated terms

3.1 Terms and definitions

No terms and definitions are listed in this document.

ISO and IEC maintain terminological databases for use in standardization at the following addresses:

- IEC Electropedia: available at http://www.electropedia.org/
- ISO Online browsing platform: available at http://www.iso.org/obp

3.2 Abbreviated terms

The abbreviations used in this document are shown in Table 1.

Table 1 – Abbreviated terms

Abbreviation	Full word	Note
STEP	Standard for the Exchange of Product Model Data,	The document for the Exchange of Product Model Data is a comprehensive ISO standard (ISO 10303 [all parts]) that describes how to represent and exchange digital product information.
DXF	Drawing Exchange Format	The Drawing Exchange Format is a CAD data file format developed by Autodesk for enabling data interoperability between AutoCAD and other programs.
IGES	Initial Graphics Exchange Specification	The Initial Graphics Exchange Specification is a vendor-neutral file format that allows the digital exchange of information among CAD systems

4 Classification of component shape data

4.1 Classification by technical drawing

The classifications by technical drawing are the following four patterns. The drawing should be managed by agreement between parts manufacturer and equipment manufacturer.